

USB-Compliant Single-cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Features

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Faster Charging than Linear
- Charge Voltage Accuracy: 0.5% at 25°C 1% from 0 to 125°C
- ±7% Input Current Regulation Accuracy
- ±7% Charge Current Regulation Accuracy
- 26V Absolute Maximum Input Voltage
- 6V Maximum Input Operating Voltage
- 1.5A Maximum Charge Rate
- Programmable through High-Speed I²C Interface(3.4Mb/s) with Fast Mode Plus Compatibility
 - Input Current
 - Fast-Charge/Termination Current
 - Charger Voltage
 - Recharge Voltage
 - Termination Enable
- 2MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint 1µH External Inductor
- 1.8V Regulated Output from VBUS for Auxiliary Circuits
- Dynamic Input Voltage Control
- Low Reverse Leakage to Prevent Battery Drain to VBUS
- 5V, 600mA Boost Mode for USB OTG for 3.2V to 4.5V Battery Input
- Available in TQFN3*3-16, DFN3*3-12 Packages.

Descriptions

The DIO59015 combines a highly integrated switch-mode charger, to minimize single-cell Lithium-ion (Li-ion) charging time from a USB power source, and a boost regulator to power a USB peripheral from the battery.

The charging parameters and operating modes are programmable through an I²C Interface that operates up to 3.4Mbps. The charger and boost regulator circuits switch at 2MHz to minimize the size of external passive components.

The DIO59015 provides battery charging in three phases: conditioning, constant current and constant voltage.

To ensure USB compliance and minimize charging time, the input current limit can be changed through the I²C by the host processor. Charge termination is determined by a programmable minimum current level.

The integrated circuit (IC) automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode, preventing leakage from the battery to the input. Charge current is reduced when the die temperature reaches 120°C, protecting the device and PCB from damage.

The DIO59015 can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery and uses the same external components used for charging the battery.

Applications

- Cell Phones, Smart Phones, PDAs
- Tablet, Portable Media Players
- Gaming Device, Digital Cameras



Ordering Information

Order Part Number	Top Marking		T _A	Package	
DIO59015CL16	59015	Green	-40 to +85°C	TQFN-16	Tape & Reel, 5000
DIO59015CD12	59015	Green	-40 to +85°C	DFN3*3-12	Tape & Reel, 5000

Pin Assignments

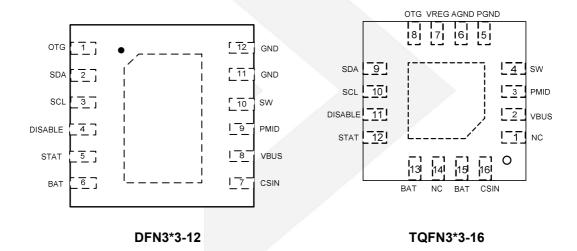


Figure 1. Pin Assignment (Top View)



Pin Definitions

Name	Description
VBUS	Charger Input Voltage and USB-OTG output voltage. Bypass with a 1µF capacitor to PGND.
NC	No Connect. No external connection is made between this pin and the IC's internal circuitry.
SCL	I ² C Interface Serial Clock. This pin should not be left floating.
PMID	Power Input Voltage. Power input to the charger regulator, bypass point for the input current sense, and high-voltage input switch. Bypass with a minimum of 10µF, 6.3V capacitor to PGND.
SDA	I ² C Interface Serial Data. This pin should not be left floating.
SW	Switching Node. Connect to output inductor.
STAT	Status. Open-drain output indicating charge status. The IC pulls this pin LOW when charging.
PGND	Power Ground. Power return for gate drive and power transistors. The connection from this pin to the bottom of CMID should be as short as possible.
OTG	On-The-Go. Enables boost regulator in conjunction with OTG_EN and OTG_PL bits (see Table 14).
CSIN	Charging current detection input terminal.
DISABLE	Charge Disable. If this pin is HIGH, charging is disabled. When LOW, charging is controlled by the I ² C registers.
VREG	Regulator Output. Connect to a 1µF capacitor to PGND. This pin can supply up to 2mA of DC load current. The output voltage is PMID, which is limited to 1.8V.
BAT	Battery Voltage. Connect to the positive (+) terminal of the battery pack. Bypass with a 0.1µF capacitor to PGND if the battery is connected through long leads.
GND	Power Ground.
AGND	Analog ground.



Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Rating" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maxim rating conditions for extended periods may affect device reliability.

	Parameter	Rating	Unit
VDLIC Voltage	Continuous	-1.4 to 26.0	V
VBUS Voltage	Pulsed, 100ms Maximum Non-Repetitive	-2.0 to 26.0	V
STAT Voltage		-0.3 to 26.0	V
PMID Voltage		6.5	V
SW, CSIN, VBAT, DISABLE Vo	oltage	-0.3 to 6.5	V
Voltage on Other Pins		-0.3 to 6.5	V
Maximum V _{BUS} Slope above 5.	5V when Boost or Charger are Active	4	V/µs
FCD	НВМ	2000	V
ESD	CDM	500	V
Junction Temperature		-40 to 150	°C
Storage Temperature		-65 to 150	°C
Lead Soldering Temperature, 1	0 Seconds	260	°C

Recommend Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended Operating conditions are specified to ensure optimal performance to the datasheet specifications. DIOO does not Recommend exceeding them or designing to Absolute Maximum Ratings.

Parameter	Rating	Unit	
Supply Voltage		4 to 6	V
Maximum Battery Voltage when Boost enabled	4.5	V	
Negative VBUS Slew Rate during VBUS Short	T _A ≤60°C	4	Wuo
Circuit, C _{MID} ≤10μF	T _A ≥60°C	2	V/μs
Ambient Temperature	-30 to +85	°C	
Junction Temperature	Junction Temperature		



Electrical Characteristics

 V_{IN} = 5V, T_A = 25°C, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Uni	
Power Supp	lies						
		V _{BUS} >V _{BUS(min)} , PWM Switching		10		mA	
I _{VBUS}	VBUS Current	V _{BUS} > V _{BUS(min)} ; PWM Enabled, Not Switching (Battery OVP Condition); I_IN Setting=100 mA		0.2		mA	
		0°C <t<sub>J<85°C, HZ_MODE=1</t<sub>		88		μΑ	
I_{LKG}	VBAT to VBUS Leakage Current	0°C <t<sub>J<85°C, HZ_MODE=1, V_{BAT}=4.2V, V_{BUS}=0V</t<sub>		1.6	15.0	μA	
	Battery is charge Current in	0°C <t<sub>J< 85°C, HZ_MODE=1, V_{BAT}=4.2V</t<sub>		5	10		
I _{BAT}	High- Impedance Mode	DISABLE=1, 0°C <t<sub>J<85°C, V_{BAT}=4.2V</t<sub>		5 10		<u>μ</u> Α	
Charger Vo	Itage Regulation						
	Charge Voltage Range		4.2		4.4	6 V	
V_{OREG}	Charge Voltage Accuracy	T _A =25°C	-0.5%		+0.5%		
		T _J =0 to 125°C	-1%		+1%		
Charging C	urrent Regulation		J		J.		
	Output Charge Current Range	V_{SHORT} < V_{BAT} < V_{OREG} , R_{SENSE} =68m Ω	550		1500	m	
I _{OCHRG}	Charge Current Accuracy	20mV ≤ V _{IREG} ≤ 40mV	-7		7	%	
	Across R _{SENSE}	V _{IREG} >40mV	-4		4	%	
Logic Level	s: DISABLE, SDA, SCL, OTG		•		•		
V _{IH}	High-Level Input Voltage		1.05			٧	
V _{IL}	Low-Level Input Voltage				0.4	٧	
I _{IN}	Input Bias Current	Input Tied to GND or V _{IN}		0.01	1.00	μ	
Charge Ter	mination Detection						
	Termination Current Range	V _{BAT} >V _{OREG} -V _{RCH} , R _{SENSE} =68mΩ	50		400	m	
	T : # 2 : #	[V _{CSIN} - V _{BAT}] from 6mV to 20mV	-25		+25	%	
$I_{(TERM)}$	Termination Current Accuracy	ent Accuracy [V _{CSIN} - V _{BAT}] from 20mV to 40mV			+10	%	
	Termination Current Deglitch Time			30		m	
1.8V Linear	Regulator				•		
V_{REG}	1.8V Regulator Output	I _{REG} from 0 to 2mA	1.7	1.8	1.9	V	



		DI059015					
	Short-Circuit Current Limit			4.8		mA	
Input Power	r Source Detection			1			
$V_{IN(MIN)}$	VBUS Input Voltage Rising	To Initiate and Pass VBUS Validation	3.75	4	4.25	V	
V _{hys}				0.3		V	
t _{VBUS_VALID}	VBUS Validation Time			30		ms	
Special Cha	arger (V _{BUS})					,	
V_{SP}	Special Charger Set point Accuracy		-3		+3	%	
Input Curre	nt Limit			l			
		REG[7:6]=00	TBD	100	TBD		
		REG[7:6]=01	470	500	530		
I _{INLIM}	Input Current Limit Threshold	REG[7:6]=10	750	800	850	mA	
		REG[7:6]=11		No limit		7	
Battery Rec	charge Threshold		1			1	
	Recharge Threshold	Below V _(OREG)	50		200	mV	
V_{RCH}	Deglitch Time	V _{BAT} Falling Below V _{RCH} Threshold		30		ms	
STAT Outpu	ut		1			1	
V _{STAT(OL)}	STAT Output Low	I _{STAT} =10mA			0.4	V	
I _{STAT(OH)}	STAT High Leakage Current	V _{STAT} =5V			1	μA	
Sleep Comp	parator	ľ				1	
V_{SLP}	Sleep-Mode Entry Threshold, V _{BUS} - V _{BAT}	4V≪V _{BAT} ≪V _{OREG} , V _{BUS} Falling	0	0.04	0.1	V	
V _{SLP-EXIT}	Sleep-Mode Exit Threshold, V _{BUS} - V _{BAT}			0.1		V	
t _{SLP_EXIT}	Deglitch Time for VBUS Rising Above V_{BAT} by V_{SLP}	Rising Voltage		30		ms	
Power Swite	ches						
	Q3 On Resistance(VBUS to PMID)	I _{IN(LIMIT)} =500mA		86			
R _{DS(ON)}	Q1 On Resistance(PMID to SW)			85		mΩ	
	Q2 On Resistance(SW to GND)			75			
Charger PW	VM Modulator						
f_{SW}	Oscillator Frequency		1.7	2	2.3	MHz	
D _{MAX}	Maximum Duty Cycle				100	%	
D _{MIN}	Minimum Duty Cycle			6		%	



		DI033013					
I _{SYNC}	Synchronous to Non-Synchronous Current Cut-Off Threshold ⁽²⁾	Low-Side MOSFET(Q2) Cycle-by- Cycle Current Limit		300		mA	
Boost Mode	Operation(OPA_MODE=1, HZ_M	ODE=0)					
V	Desat Outsut Voltage at V/PLIS	$2.5V < V_{BAT} < 4.5V$, I_{LOAD} from 0 to 200 mA	4.88	5.15	5.25	V	
V _{BOOST} Boost Output Voltage at VBUS		$3.0V < V_{BAT} < 4.5V$, I_{LOAD} from 0 to 500 mA	4.85	5.15	5.25	V	
I _{BAT(BOOST)}	Boost Mode Quiescent Current	PFM Mode, V _{BAT} =3.6V, I _{OUT} =0		500		μA	
I _{LIMPK(BST)}	Q2 Valley Current Limit		1200	1600	2000	mA	
10/10	Minimum Battery Voltage for Boost	While Boost Active		2.6		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
UVLO _{BST}	Operation	To Start Boost Regulator		2.7		V	
Battery Detection							
I _{DETECT}	Battery Detection Sink Current (1)	Begins after Charge Termination Detected		-10		mA	
t _{DETECT}	Battery Detection Time			30		ms	
Protection a	and Timers						
) (DI 10	VBUS Over-Voltage Shutdown	V _{BUS} Rising	5.82	6	6.2	V	
VBUS _{OVP}	Hysteresis	V _{BUS} Falling		200		mV	
I _{LIMPK(CHG)}	Q1 Cycle-by-Cycle Peak Current Limit	Charge Mode		3		А	
	Battery Short-Circuit Threshold	V _{BAT} Rising		2		V	
V _{SHORT}	Hysteresis	V _{BAT} Falling		100		mV	
I _{SHORT}	Linear Charging Current	V _{BAT} <v<sub>SHORT</v<sub>		30		mA	
_	Thermal Shutdown Threshold	T _J Rising		145		. ℃	
T _{SHUTDWN}	Hysteresis	T _J Falling		10			
T _{CF}	Thermal Regulation Threshold	Charge Current Reduction Begins		120		°C	
t _{INT}	Detection Interval			30		ms	

Notes:

- 1. Negative current is current flowing from the battery to VBUS (discharging the battery).
- 2. Q2 always turn on for 60ns, then turns off if current is below $I_{\mbox{\scriptsize SYNC}}.$



I²C Timing Specifications

Symbol	Parameter	Test Conditions	Min	Тур	Max	Uni	
		Standard Mode			100		
	SCI Clock Fraguency	Fast Mode			400		
f _{SCL}	SCL Clock Frequency	High-Speed Mode, C _B ≤100pF			3400	kHz	
		High-Speed Mode, C _B ≤400pF			1700		
	Bus-Free Time between STOP	Standard Mode		4.7			
t _{BUF}	and START Conditions	Fast Mode		1.3		μs	
	07407 0 4 107407	Standard Mode		4		μ	
$t_{\text{HD;STA}}$	START or Repeated START Hold Time	Fast Mode		600		n	
	Hold Tillle	High-Speed Mode		160		n	
		Standard Mode		4.7		μ	
	SCL LOW Pariod	Fast Mode		1.3		μ	
t _{LOW}	SCL LOW Period	High-Speed Mode, C _B ≤100pF		160		n	
		High-Speed Mode, C _B ≤400pF		320		n	
t _{нісн}		Standard Mode		4		μ	
	SCL HIGH Period	Fast Mode		600		n	
		High-Speed Mode, C _B ≤100pF		60		n	
		High-Speed Mode, C _B ≤400pF		120		n	
		Standard Mode		4.7		μ	
$t_{\text{SU;STA}}$	Repeated START Setup Time	Fast Mode		600		n	
		High-Speed Mode		160		n	
		Standard Mode		250			
$t_{\text{SU;DAT}}$	Data Setup Time	Fast Mode		100		ns	
		High-Speed Mode		10			
		Standard Mode	0		3.45	μ	
	Data Hold Time	Fast Mode	0		900	n	
t _{HD;DAT}	Data Hold Time	High-Speed Mode, C _B ≤100pF	0		70	n	
		High-Speed Mode, C _B ≤400pF	0		150	n	
		Standard Mode	20+	-0.1C _B	100		
	SCL Rise Time	Fast Mode	20+	-0.1C _B	300		
t _{RCL}	SOL RISE TIME	High-Speed Mode, C _B ≤100pF		10	80	n	
		High-Speed Mode, C _B ≤400pF		20	160		
		Standard Mode	20+	0.1C _B	300		
t_	SCI Fall Time	Fast Mode	20+	-0.1C _B	300	_ [
t _{FCL}	SCL Fall Time	High-Speed Mode, C _B ≤100pF		10	40	n	
		High-Speed Mode, C _B ≤400pF		20	80		



	SDA Rise Time	Standard Mode	20+0		300	
t _{RDA}	Rise Time of SCL after a	Fast Mode	20+	0.1C _B	300	-
t _{RCL1}	Repeated START Condition and	High-Speed Mode, C _B ≤100pF		10	80	ns
	after ACK Bit	High-Speed Mode, C _B ≤400pF		20	160	
	SDA Fall Time	Standard Mode	20+	20+0.1C _B		
		Fast Mode	20+0.1C _B		300	
t _{FDA}		High-Speed Mode, C _B ≤100pF		10	80	ns
		High-Speed Mode, C _B ≤400pF		20	160	
		Standard Mode		4		μs
t _{su;sto}	Stop Condition Setup Time	Fast Mode		600		ns
		High-Speed Mode		160		ns
Св	Capacitive Load for SDA, SCL				400	pF

Timing Diagrams

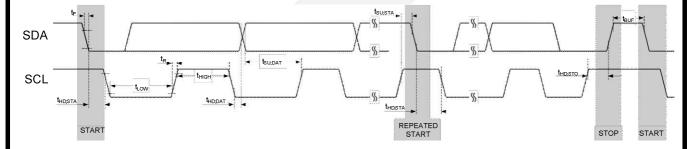
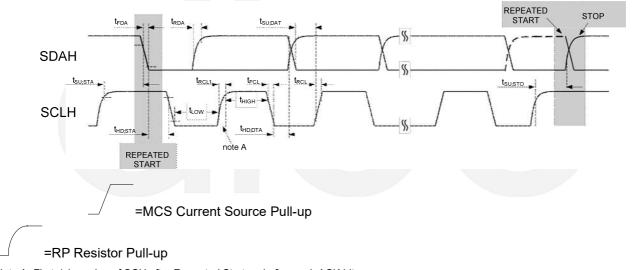


Figure 2. I²C Interface Timing for Fast and Slow Modes



Note A: First rising edge of SCH after Repeated Start and after each ACK bit.

Figure 3. I²C Interface Timing for High-Speed Mode



Typical Application

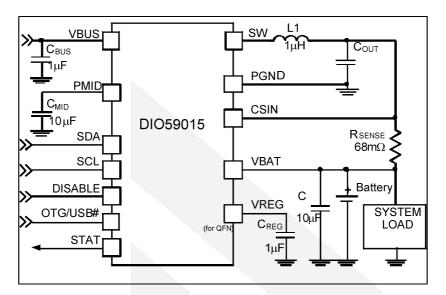


Figure 4. Typical Application

Block Diagram

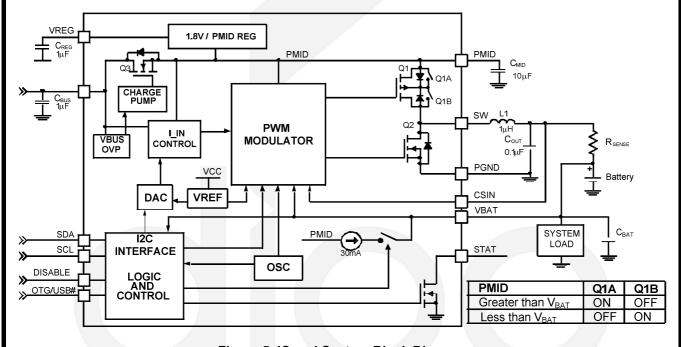
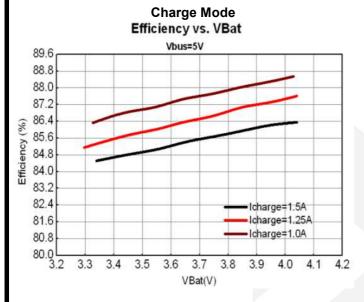


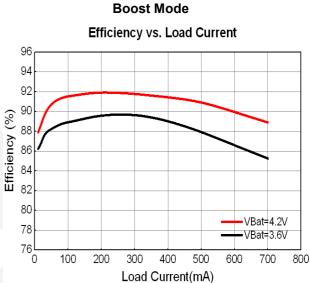
Figure 5. IC and System Block Diagram



Typical Performance Characteristic

Typical value: T_A = 25°C, V_{IN}=5V, unless otherwise specified.



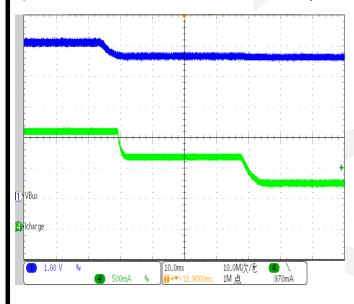


Charge Mode Typical Characteristics

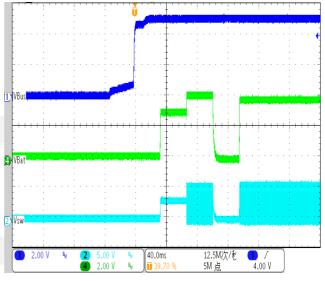
Unless otherwise specified, V_{OREG}=4.2V, V_{BUS}=5.0V, and T_A=25°C.

VBUS BASED DPM

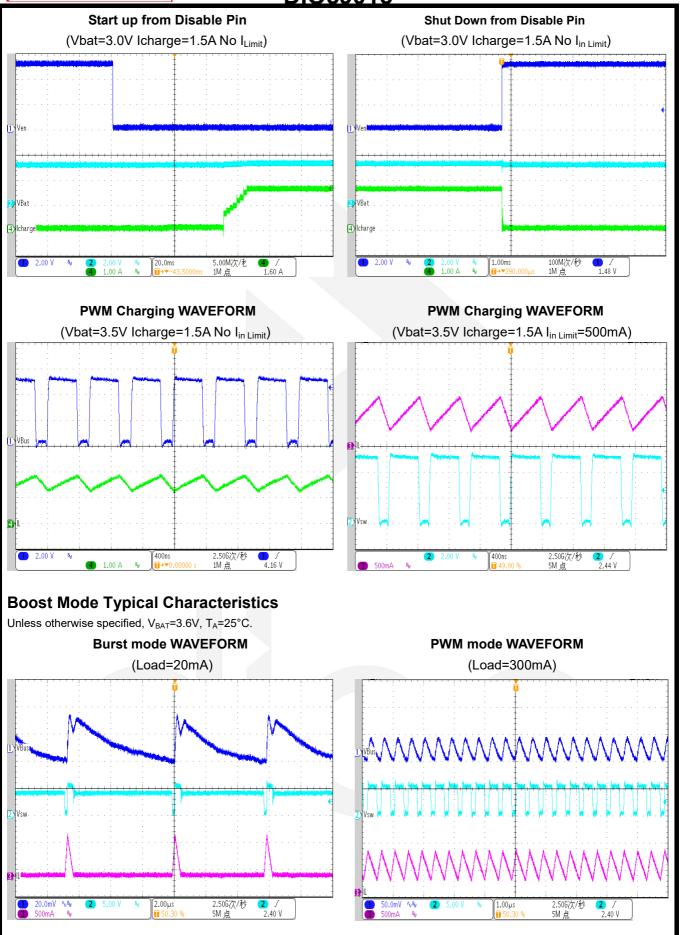
(Vbus=5V down to 4.5V Vbat=3.0V V_{DPM}=4.525V)



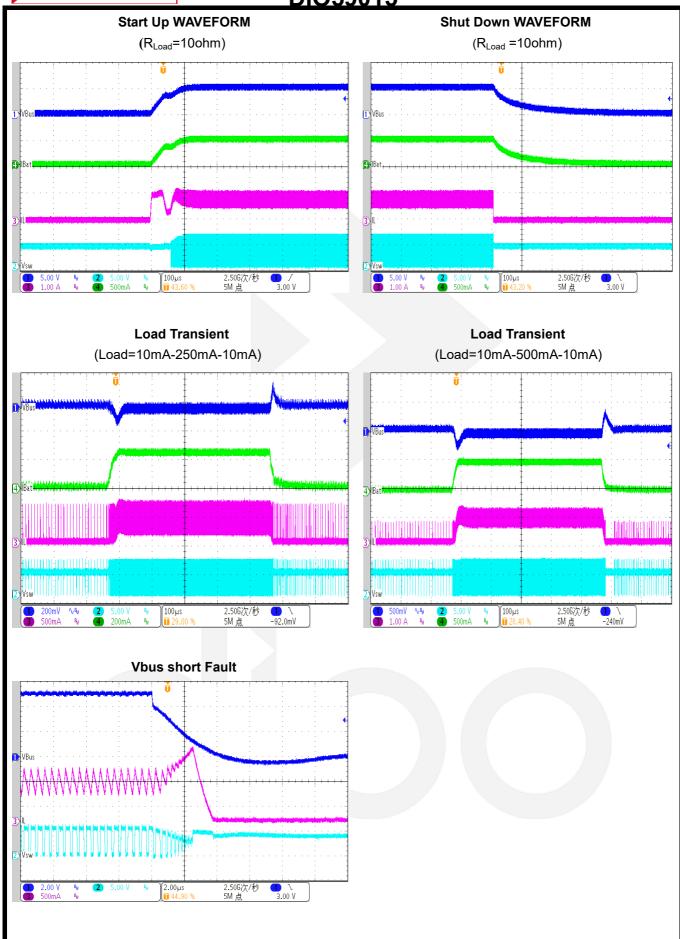
No Battery at VBUS Power-up













Application Information

Circuit Description/Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

DIO59015 combines a highly integrated synchronous buck regulator for charging with a synchronous boost regulator, which can supply 5V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

The DIO59015 has three operating modes:

- 1. Charge Mode:
 - Charge a signal-cell Li-ion or Li-polymer battery.
- 2. Boost Mode:
 - Provides 5V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.
- High-Impedance Mode:
 - Both the boost and charging circuits are OFF in this mode. Current flow from VBUS to the battery or from the battery to VBUS is blocked in this mode. This mode consumers very little current from VBUS or the battery.

Charge Mode

In charge Mode, DIO59015 employs four regulation loops:

- 1. Input Current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I²C interface.
- Charging Current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.
- 3. Charge Voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage roses the battery's internal impedance and R_{SENSE} work in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R_{SENSE} drops below the I_{TERM} threshold.
- 4. Temperature: If the IC's junction temperature reaches 120℃,charge current is reduced until the IC's temperature stabilizes at 120℃.
- 5. An additional loop limits the amount of drop on VBUS to a programmable voltage (V_{SP}) to accommodate "special chargers" that limit current to a lower current than might be available from a "normal" USB wall charger.

Battery Charging Curve

If the battery voltage is below V_{SHORT} , a linear current source pre-charges the battery until V_{BAT} reaches V_{SHORT} . The PWM charging circuit is then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The DIO59015 is designed to work with a current-limited input source at VBUS. During the current regulation phase of charging, I_{INLIM} or the programmed charging current limits the current available to charge the battery and



power the system. The effect of I_{INLIM} on I_{CHARGE} can be see in Figure 7.

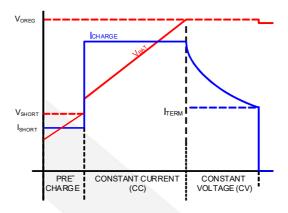


Figure 6. Charge Curve, I_{CHARGE} Not Limited by I_{INLIM}

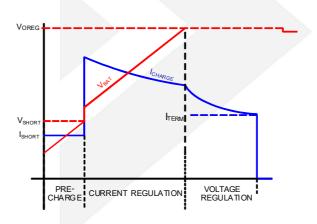


Figure 7. Charge Curve, I_{INLIM} Limits I_{CHARGE}

Assuming that V_{OREG} is programmed to the cell's fully charged "float" voltage, the current that the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to V_{OREG} declines, and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting he TE bit (REG[3]).

The charger output or "float" voltage can be programmed by the OREG bits from 4.2V to 4.44V in 20mV increments, as shown in Table 1.

Table 1. OREG Bits (OREG[7:2]) vs. Charge V_{OUT} (V_{OREG}) Float Voltage

Decimal	Hex	VOREG
0~35	00~23	4.20
36~40	24~28	4.30
41~43	29~2B	4.35
44~62	2C~3E	4.40

The following charging parameters can be programmed by the host through I²C.



Table 2. Programmable Charging Parameters

Parameter	Name	Register
Output Voltage Regulation	V_{OREG}	REG2[7:2]
Battery Charging Current Limit	I _{OCHRG}	REG4[6:4]
Input Current Limit	I _{INLIM}	REG1[7:6]
Charge Termination Limit	I _{TERM}	REG4[2:0]

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below V_{OREG}-V_{RCH}
- VBUS Power on Reset (POR) clears and the battery voltage is below the V_{SHORT}.
- CE or HZ_MODE is rest through I²C write to CONTROL1 (Reg1) register.

Charge Current Limit (I_{OCHARGE})

Table 3. I_{OCHARGE} (REG4 [6:4]) Current as Function of I_{OCHARGE} Bits and R_{SENSE} Resistor Values

DEC	BIN	HEX	V _{RSENSE}	I _{OCHARG}	_E (mA)
DLC	BIN	IILX	(mV)	68mΩ	100mΩ
0	000	00	37.5	551	375
1	001	01	44.4	653	444
2	010	02	51.2	753	512
3	011	03	57.5	846	575
4	100	04	71.3	1048	713
5	101	05	78.1	1149	781
6	110	06	91.9	1351	919
7	111	07	101.8	1498	1018

Table 4. V_{RCH} (REG7 [1:0]) Recharge Voltage

DEC	BIN HEX		V _{RCH} (mV)
0	00	00	50
1	01	01	100
2	10	02	150
3	11	03	200

Termination Current Limit

Current charge termination is enabled when TE (REG1[3])=1. Typical termination current values are given in Table 5.



Table 5. I_{TERM} Current as Function of I_{TERM} Bits (REG4[2:0]) and R_{SENSE} Resistor Values

NIVI		TEININ (e 1/ OLNOL		
	V _{RSENSE}	I _{TERM} (mA)			
I _{TERM}	(mV)	68mΩ	100mΩ		
0	3.1	46	31		
1	6.3	92	63		
2	9.4	138	94		
3	12.5	184	125		
4	15.6	230	156		
5	18.8	276	188		
6	21.9	322	219		
7	25	368	250		

When the charge current falls below I_{TERM}, PWM charging stops and the STAT bits change to READY (00) for about 30ms while the IC determines whether the battery and charging source are still connected. STAT then changes to CHARGE DONE (10), provided the battery and charger are still connected.

PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulator the output voltage and battery charge currents. The synchronous rectifier (Q2) has a current limit that which off the FET when the current is negative by more than 300mA peak. This prevents current flow from battery.

V_{BUS} POR/Non-Compliant Charger Rejection

When the IC detects that VBUS has risen above $V_{\text{IN(MIN)}}(4.3\text{V})$, the IC applies a 250Ω load from VBUS to GND. To clear the VBUS POR (Power-On-Reset) and begin charging, VBUS must remain above $V_{\text{IN(MIN)}}$ and below VBUS_{OVP} for $t_{\text{VBUS}_\text{VALID}}$ (30ms) before the IC initiates Charging. The VBUS validation sequence always occurs charging is initiated or re-initiated (for example, after a VBUS OVP fault or a V_{RCH} recharge initiation).

t_{VBUS VALID} ensures that unfiltered 50/60Hz chargers and other non-compliant chargers are rejected.

Input Current Limiting

To minimize charging time without overloading VBUS current limitations, the IC's input current limit can be programmed by the I_{INLIM} bits (REG1[7:6]).

Table 6. Input Current Limit

I _{INLIM} REG[7:6]	Input Current Limit
00	100 mA
01	500 mA
10	800 mA
11	No limit



Flow Charts

DIO59015

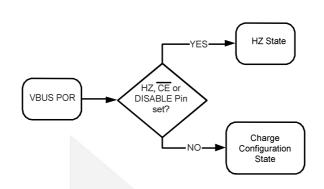


Figure 8. Charger VBUS POR

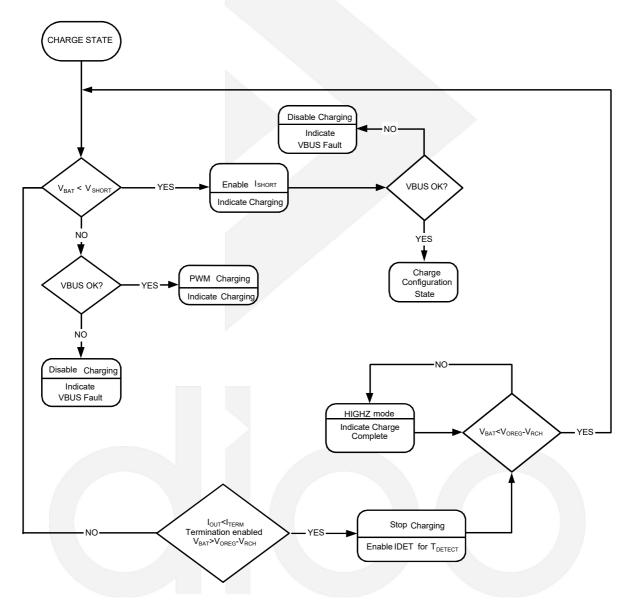


Figure 9. Charge Mode

Special Charger

The DIO59015 has additional functionality to limit input current in case a current-limited "special charger" is supplying VBUS. These slowly increase the charging current until either.

■ I_{INLIM} or I_{OCHARGE} is reached



 $V_{BUS}=V_{SP}$.

If V_{BUS} collapses to V_{SP} when the current is ramping up, the DIO59015 charge with an input current that keeps V_{BUS}=V_{SP}. When the V_{SP} control loop is limiting the charge current, the SP bit (REG5[4]) is set.

Table 7. V_{SP} as Function of SP Bits (REG5[2:0])

;			
DEC	BIN	HEX	V _{SP}
0	000	00	4.225
1	001	01	4.300
2	010	02	4.375
3	011	03	4.450
4	100	04	4.525
5	101	05	4.600
6	110	06	4.675
7	111	07	4.750

Thermal Regulation and Protection

When the IC's junction temperature reaches T_{CF} (about 120℃), the charger reduces its output current to 550mA to prevent overheating. If the temperature increases beyond T_{SHUTDOWN}; charging is suspended, the FAULT bits are set to 101, and STAT is pulsed HIGH. In Suspend Mode, all timers stop and the state of the IC's logic is preserved. Charging resumes at programmed current after the die cools to about 120℃.

Additional θ_{JA} data points, measured using the DIO59015 evaluation board, are given in Table 8 (measured with TA=25 °C). Note that as power dissipation increases, the effective θ_{JA} decreases due to the larger difference between the die temperature and ambient.

Table 8. Evaluation Board Measured θ_{JA}

Power (W)	θ _{JA}
0.504	54°C/W
0.844	50°C/W
1.506	46°C/W

Charge Mode Input Supply Protection

Sleep Mode

When V_{BUS} falls below $V_{BAT}+V_{SLP}$, and V_{BUS} is above $V_{IN(MIN)}$. the IC enters Sleep Mode to prevent the battery from draining into VBUS. During Sleep Mode, reverse current is disabled by body switching Q1.

Input Supply Low-Voltage Detection

The IC continuously monitors VBUS during charging. If V_{BUS} falls below V_{IN(MIN)}, the IC:

- Terminates charging.
- Pulses the STAT pin, sets the STAT bits to 11, and sets the FAULT bits to 011.

If V_{BUS} recovers above the $V_{IN(MIN)}$ rising threshold after time t_{INT} (about two seconds), the charging process is repeated. This function prevents the USB power bus from collapsing or oscillating when the IC is connected to a suspended USB port or a low-current-capable OTG device.

Input Over-Voltage Detection

When the V_{BUS} exceeds VBUS_{OVP}, the IC:



- 1. Turns off Q3
- 2. Suspends charging
- 3. Sets the FAULT bits to 001, sets the STAT bits to 11, and pulses the STAT pin.

When V_{BUS} falls about 150mV below VBUS_{OVP}, the fault is cleared and charging resumes after V_{BUS} is revalidated (see VBUS POR/Non-Compliant Charger Rejection).

VBUS Short While Charging

If VBUS is shorted with a very low impedance while the IC is charging with II_{NLIMIT} =100mA, the IC may not meet datasheet specifications until power is removed. To trigger this condition, V_{BUS} must be driven from 5V to GND with a high slew rate. Achieving this slew rate requires a 0Ω short to the USB cable less than 10cm from the connector.

Charge Mode Battery Detection & Protection

VBAT Over-Voltage Protection

The OREG voltage regulation loop prevents V_{BAT} from overshooting the OREG voltage when the battery is removed. When the PWM charger runs with no battery, the TE bit is not set and a battery is inserted that is charged to a voltage higher than V_{OREG} ; PWM pulses stop. If no further pulses occur for 30ms, the IC sets the FAULT bits to 100, sets the STAT bits to 11, and pulses the STAT pin.

Battery Detection During Charging

The IC can detect the presence, absence. During normal charging, once VBAT is close to VOREG and the termination charging, once VBAT is close to VOREG and the termination charge current is detected, the IC terminates charging and sets the STAT bits to 10. It then turns on a discharge current, I_{DETECT}, for t_{DETECT}. If VBAT is still above 2V, the battery is present and the IC sets the FAULT bits to 000. If VBAT is below 2V, the battery is absent and the IC:

- 1. Operation with No Battery
- 2. Sets the FAULT bits to 111.

Battery Short-Circuit Protection

If the battery voltage is below the short-circuit threshold (V_{SHORT}); a linear current source, I_{SHORT} , supplies V_{BAT} until V_{BAT} > V_{SHORT} .

System Operation with No Battery

The DIO59015 continues charging after VBUS POR with the default parameters, regulating the V_{BAT} line to 3.78V (if set V_{OREG} at 4.2V). In this way, the DIO59015 can start the system without a battery. Re-connect power to VBUS or reset ENN pin, IC can exit No Battery Mode.

Charger Status/Fault Status

The STAT pin indicates the operating condition of the IC and provides a fault indicator for interrupt driven systems.

Table 9. STAT Pin Function

EN_STAT	Charge State	STAT Pin
Х	No Charging	OPEN
1	Charging	LOW
Х	Fault	2Hz Pulse



The FAULT bits (Reg0[2:0]) indicate the type of fault in Charge Mode (see Table 10).

Table 10. Fault Status Bits During Charge Mode

ı	Fault Bit		Fault Description
B2	B1	В0	Fault Description
0	0	0	Normal (No Fault)
0	0	1	VBUS OVP
0	1	0	Sleep Mode
0	1	1	Poor Input Source
1	0	0	Battery OVP
1	0	1	Thermal Shutdown
1	1	0	N.A
1	1	1	No Battery

Charge Mode Control Bits

Setting either HZ_MODE or CE through I²C disables the charger and puts the IC into High-Impedance Mode.

Table 11. DISABLE Pin and CE Bit Functionality

			_
Charging	DISABLE Pin	CE	HZ_MODE
ENABLE	0	0	0
DISABLE	X	1	X
DISABLE	X	X	1
DISABLE	1	X	Х

Operational Mode Control

OPA_MODE (REG1[0]) and the HZ_MODE (REG1[1]) bits in conjunction with the FAULT state define the operational mode of the charger. Before VBUS connected to power source, IC should enter charge mode.

Table 12. Operation Mode Control

HZ_MODE	OPA_MODE	FAULT	Operation Mode
0	0	0	Charge
0	X	1	No charging
0	1	0	Boost
1	X	Х	High Impedance

Boost Mode

Boost Mode can be enabled if OTG pin and OPA_MODE bits as indicated in Table 13. The OTG pin ACTIVE state is 1 if OTG_PL=1 and 0 when OTG_PL=0.

If boost is active using the OTG pin, Boost Mode is initiated even if the HZ_MODE=1. The HZ_MODE bit overrides the OPA_MODE bit.

Table 13. Enabling Boost

OTG_EN	OTG Pin	HZ_MODE	OPA_MODE	BOOST
1	ACTIVE	Х	Х	Enabled
Х	Х	0	1	Enabled
Х	ACTIVE	Х	0	Disabled
0	Х	1	Х	Disabled
1	ACTIVE	1	1	Disabled
0	ACTIVE	0	0	Disabled



Boost COT Control

The IC uses a constant on-time and valley current detect to regulate VBUS. The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During COT Mode, the output voltage drops slightly as the input current rises. With a constant V_{BAT} , this appears as a constant output resistance.

The "droop" caused by the output resistance when a load is applied allows the regulator to respond smoothly to load transient with no undershoot from the load line. This can be seen in and Figure 10

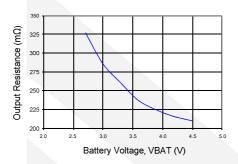


Figure 10. Output Resistance (R_{OUT})

V_{BUS} as a function of I_{LOAD} can be computed when the regulator is in PWM Mode (continuous conduction) as:

$$V_{OUT}=5.15-R_{OUT}\cdot I_{LOAD}$$
 EQ.1

At V_{BAT} =3.3V, and I_{LOAD} =200mA, V_{BUS} would drop to:

$$V_{OUT}$$
=5.15-0.26·0.2=5.098V EQ.1A

At V_{BAT}=2.7V, and I_{LOAD}=200mA, V_{BUS} would drop to:

$$V_{OUT}$$
=5.15-0.327·0.2=5.085V EQ.1B

PFM Mode

If VBUS>VREF_{BOOST} (nominally 5.07V) when the valley current comes to 0, the regulator enters PFM Mode. Boost pulses are inhibited until V_{BUS} <VREF_{BOOST}. Once V_{BUS} <VREF_{BOOST}, boost pulses are allowed for one or several times until V_{BUS} >VREF_{BOOST}. Therefore the regulator behaves like a burst mode regulator, with the average of its output voltage ripple at 5.07V in PFM Mode.

Table 14. Boost PWM Operating States

Mode	Description	Invoked When
LIN	Linear Startup	V _{BAT} >V _{BUS}
SS	Boost Soft-Start	V _{BUS} <v<sub>BST</v<sub>
BST	Paget Operation Mode	V _{BAT} >UVLO _{BST} and SS
БОТ	Boost Operation Mode	Completed

Startup

When the boost regulator is shut down, current flow is prevented from V_{BAT} to V_{BUS} , as well as reverse flow from V_{BAT} .

LIN State

When EN rises, if V_{BAT} >UVLO_{BST}, the regulator attempts to bring PMID within 200mV of VBAT using an internal 450mA current source from VBAT (LIN State). If PMID has not achieved V_{BAT} - 200mV after 500 μ s, a FAULT state



is initiated.

SS State

When PMID> V_{BAT} -200mV, the boost regulator begins switching with a SS modulator. The output slews up slowly and smoothly until V_{BUS} = $VREF_{BOOST}$.

If the output fails to achieve set point (VBST) within SS time, normally 128µs, a fault state is initiated.

BST State

This is the normal operating mode of the regulator. The regulator uses a constant on-time and valley current detect modulation scheme. The minimum t_{ON} is proportional to $\frac{V_{OUT} - V_{IN}}{V_{OUT}}$, which keeps the regulator's switching frequency reasonably constant in CCM.

To ensure the VBUS does not pump significantly above the regulation point, the boost switch remains off as long as FB>V_{REF}.

Boost Faults

If a Boost FAULT OCCURS:

- 1. OPA_MODE bit is reset.
- 2. The power stage is in High-Impedance Mode.
- 3. The FAULT bits (REG0[2:0]) are set per Table 15.

Restart After Boost Faults

If boost was enabled with the OPA_MODE bit and OTG_EN=0, Boost Mode can only be enabled through subsequent I²C commands since OPA_MODE is reset on boost faults. If OTG_EN=1 and the OTG pin is still ACTIVE (see Table 13), the boost restarts after a 5.2ms delay, as shown in Figure 11. If the fault condition persists, restart is attempted every 10ms until the fault clears or an I²C command disables the boost.

Table 15. Fault Bits During Boost Mode

F	Fault Bit		Foult Description
B2	B1	В0	Fault Description
0	0	0	Normal (no fault)
0	0	1	V _{BUS} >VBUS _{OVP}
0	1	0	VBUS fails to achieve the voltage required to advance to the next state during soft-start or sustained (>50µs) current limit during the BST state.
0	1	1	N/A: This code does not appear.
1	0	0	N/A: This code does not appear.
1	0	1	Thermal shutdown
1	1	0	N/A: This code does not appear.
1	1	1	N/A: This code does not appear.



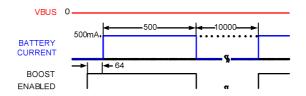


Figure 11. Boost Response Attempting to Start into VBUS Short Circuit (Times in µs)

VREG Pin

The 1.8V regulated output on this pin can be disabled through I²C by setting the DIS_VREG bit (REG5[6]). VREG can supply up to 2mA. This circuit, which is powered from PMID, is enabled only when PMID>VBAT and does not drain current from the battery. During boost, VREG is off. It is also off when the HZ MODE bit (REG1[1])=1.

Monitor Register (Reg10H)

Additional status monitoring bits enable the host processor to have more visibility into the status of the IC. The monitor bits are real-time status indicators.

I²C Interface

The DIO59015's serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Mode I2C-Busspecifications. The SCL line is an input and the SDA line is abi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and signaling ACK. All data is shifted in MSB (bit 7) first.

Slave Address

Table 16. I²C Slave Address Byte

Part Type	7	6	5	4	3	2	1	0
DIO59015	1	1	0	1	0	1	0	R/W

In hex notation, the slave address assumes a 0LSB. The hex slave address for the DIO59015 is D4H and is D6H for all other parts in the family.

Bus Timing

As shown in Figure 12, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

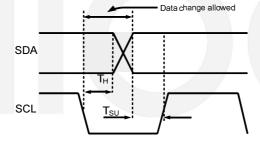


Figure 12. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCLHIGH.A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCLHIGH, as shown in Figure 13.



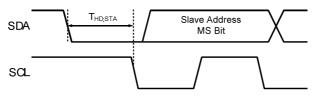


Figure 13. Start Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 14.

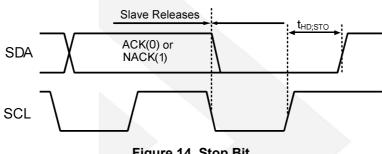


Figure 14. Stop Bit

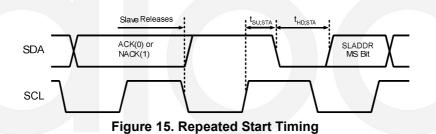
During a read from the DIO 59015 (Figure 16, Figure 17), the master issues a Repeated Start after sending the register address and before resending the slave address. The Repeated Start is a 1-to-0transition on SDA while SCL is HIGH, as shown in Figure 15.

High-Speed (HS) Mode

The protocols for High-Speed(HS), Low-Speed(LS), and Fast-Speed(FS) Modes are identical except the bus speed for HS Mode is 3.4MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a start condition. The master code is sent in Fast or Fast Plus Mode (less than1MHz clock); slaves do not ACK this transmission.

The master then generates a repeated start condition (Figure 15) that causes all slaves on the bus to switch to HS Mode. The master then sends I²C packets, as described above, using the HS Mode clock rate and timing.

The bus remains in HS Mode until a stop bit (Figure 14) is sent by the master. While in HS Mode, packets are separated by repeated start conditions (Figure 15).



Read and Write Transactions

The figure below outline the sequences for data read and write. Bus control is signified by the shading of the

Master Drives Bus Slave Drive Bus packet, defined as . All addresses and data are MSB first.



Table 17. Bit Definitions for Figure 16, Figure 17

Symbol	Definition								
S	START, see Figure 13								
Α	ACK. The slave drives SDA to 0 to acknowledge the								
	preceding packet.								
Ā	NACK. The slave sends a 1 to NACK the preceding packet.								
R	Repeated START, see Figure 15								
Р	STOP, see Figure 14.								



Figure 16. Write Transaction



Figure 17. Read Transaction

Register Bit Definitions

1 CONTROLO Register (0x00) Default Value=X1XX0XXX

1 CONTRO	DL0 Register	r (0x00) Default Value=X1)	(X0XXX					
Bit	Bit 7	Bit 6	Bit	Bit	Bit 3	Bit 2	Bit 1	Bit 0
NAME	Reserved	EN_STAT	ST	AT	BOOST		FAULT	
R/W	R/W	R/W	F	₹	R	R		
	Unused	0:	00 : C	harge	0:	for Charge Mode:		
		Prevents STAT pin from	Ready	1	Boost does	000 = Normal (1	No Fault)	
		going LOW during charging;	01 : C	harge	not operate	001 = VBUS O\	/P	
		STAT pin still pulses to	in prog	gress	1 : Boost	010 = Sleep Mo	ode	
		enunciate faults	10 : C	harge	operates	011 = Poor Inpเ	ut Source	
		1 : Enables STAT pin LOW	done			100 = Battery C	VP	
		when IC is charging.	11 : Fa	ault		101 = Thermal	Shutdown	
						110 = N.A		
						111 = No Batter	ry	
						for Boost Mode		
Function						000 = Normal (r	no fault)	
						001 = VBUS>V	BUS _{OVP}	
						010 = VBUS fai	ls to achieve the	voltage required
						to advance to the	ne next state duri	ng soft-start or
						sustained (>50)	us) current limit d	uring the BST
						state.		
						011 = VBAT <uvlobst< td=""><th></th></uvlobst<>		
						100 = N/A: This	code does not a	ppear.
						101 = Thermal	shutdown	
						110 = N/A: This	code does not a	ppear.
						111 = N/A: This	code does not a	ppear.



2 CONTRO	DL1 Regis	ter (0x	01) D	efault '	Value=0111 0000 (70h)			
Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	I _{INLIM} Reserved		ved	TE	CE	HZ_MODE	OPA_MODE	
R/W	R/W R/W		W	R/W	R/W	R/W	R/W	
	Input current		Unused		0 :Disable charge current	0 :Charger	0:Not High-Impedance	0 :Charge
	limit:				termination.	enabled.	Mode.	Mode.
Function	00:100 m	nΑ			1 : Enable charge current	1 : Charger	1 : High-Impedance	1:Boost Mode.
Function	01 :500 r	nΑ			termination.	disabled.	Mode.	
	10 :800 r	10 :800 mA						
	11: No lir	nit						

3 OREG Register (0x02) Default Value=0000 1010 (0Ah)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	OREG		ı	OTG_PL	OTG_EN			
R/W			R/	W			R/W	R/W
	Charger o	output "float"	' voltage;				0 :OTG pin active LOW.	0:
Function	programm	nable from 4	1.2 to 4.4V;	defaults to (000010 (4.2	1 : OTG pin active HIGH.	Disables OTG pin.	
Function	00 0000~	10 0011 : 4.	.2V; 10 0	100~10 100	00 : 4.3V;		1 : Enables OTG pin.	
	10 1001~	10 1011: 4.3	35V; 10 1	100~11 11	10: 4.4V;			

4 IC_INFO Register (0x03) Default Value=1001 0100 (94h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
NAME	Reserved				PN	ı	REV		
R/W	R			R			R		
Function	Identifies the I	C supplier.		Part nun	nber bits.		IC Revision, revision decimal of these three b	,	

O IDAI INC	gister (UXU4)	Delault value=1000 1001 (091)									
Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
NAME	Reserved	V(I _{OCHARGE})			Reserved	V(I _{TERM})					
R/W	R/W	R/W			R/W	R/W					
	0 =	Programs the m	aximum charge o	current	Unused	Sets the curren	t used for chargi	ng termination			
	Unused	000: 37.5mV;	001: 44.4mV;			000 : 3.1mV;	001: 6.3mV;				
		010: 51.2 mV;	011: 57.5 mV;			010: 9.4mV;	011: 12.5mV;				
Function		100: 71.3 mV;	101: 78.1 mV;			100: 15.6mV;	101: 18.8mV;				
runction		110: 91.9 mV;	111: 101.8 mV	′ ;		110: 21.9mV;	111: 25mV;				
		The charge curre	nt step (I _{OCHARGE})	is calculated		The termination current step (I _{TERM}) can be					
		using:				calculated using:					
		I _{OCHARGE} = V(I	OCHARGE)/R _{SENSE} ;			$I_{TERM} = V(I_{TER})$	M)/ R _{SENSE} ;				



6 SP_CHA	RGER Reg	ister (0x05) Defa	ult Value=0	X1X X100				
Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	Reserve	DIS_VREG	Reserve	SP	EN_LEVEL		VSP	
R/W	R/W	R/W	R/W	R	R		R/W	
	Unused	0 :1.8V regulator is	Unused	0 :Special charger is not	0 : DISABLE pin	Special ch	narger inpu	t
		ON.		active (V _{BUS} is able to stay	is LOW .	regulation	voltage	
		1 : 1.8V regulator		above V _{SP}).	1 : DISABLE pin	000: 4.225	5V; 001: 4.	300V;
Function		is OFF.		1 : Special charger has	is HIGH.	010: 4.375	5V; 011: 4.	450V;
		DFN-12: Default=1		been detected and V _{BUS} is		100: 4.525	5V; 101: 4.	600V;
		QFN-16: Default=0		being regulated to V _{SP} .		110: 4.675	5V; 111: 4.	750V

7 Register (0x07) Default Value=0000 0001 (01h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME		Reserved		Reserved	Rese	rved	V _{RCH}	
R/W	R/W			R/W	R/	W	R/W	
	Unused			Unused	Unu	sed	Recharge voltage of V _{OREG} drops.	
Function	on l						00: 50mV; 01: 100mV;	
							10: 150mV; 11	: 200mV

8 MONITOR Register (0x10h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	I _{TERM_CMP}	V _{BAT_CMP}	LINCHG	T_120	Існ	I _{BUS}	V _{BUS_VALID}	cv
R/W	R	R	R	R	R	R	R	R

Function I_{TER}

I_{TERM_CMP}:

ITERM comparator output. 0: V_{CSIN}-V_{BAT}>V_{ITERM}. 1: V_{CSIN}-V_{BAT}<V_{ITERM}

V_{BAT CM}

Output of VBAT comparator in charging mode, 0: VBAT < VSHORT 1: VBAT > VSHORT

LINCHG

In charging mode ,0: 30mA linear charger Not Enable; 1: 30mA linear charger Enable.

T_120

Thermal regulation comparator 0: T_J<120°C; 1: T_J>120°C

I_{CHG}

In charging mode, 0: Charging Current Controlled by I_{CHARGE} Control Loop .1: Charging Current Not Controlled by I_{CHARGE} Control Loop.

IBUS

In charging mode,0: I_{BUS} Limiting Charging Current. 1: Charge Current Not Limited by I_{BUS}

 $V_{\text{BUS_VALID}}$

When V_{BUS} > V_{BAT} ,0: V_{BUS} Not Valid 1: V_{BUS} is Valid

C۷

In charging mode. 0:Constant Current Charging. 1:Constant Voltage Charging.

Note: Register (0x10h) is for Charge mode only.

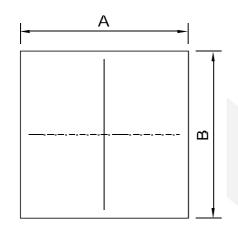


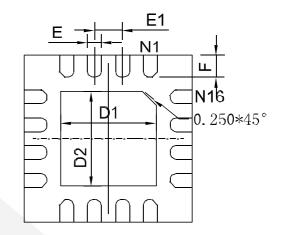
PCB Layout Recommendations

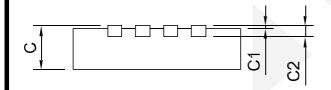
Bypass capacitors should be placed as close to the IC as possible. In particular, the total loop length for CMID should be minimized to reduce overshoot and ringing on the SW, PMID, and VBUS pins. All power and ground pins must be routed to their bypass capacitors, using top copper whenever possible. Copper area connecting to the IC should be maximized to improve thermal performance if possible.



Physical Dimensions: TQFN3*3-16

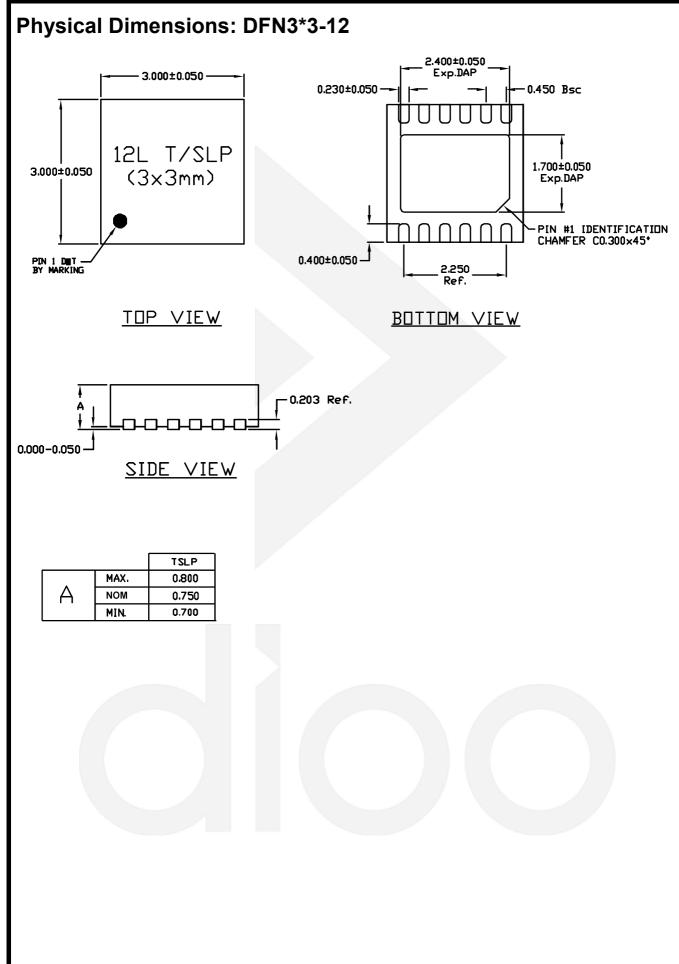






COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)									
Symbol	MIN	MAX							
Α	2.9	3.0	3.1						
В	2.9 3.0 3.1								
С	0.70 0.75 0.80								
C1	0 0.025 0.05								
C2		0.203TYP							
D1		1.70 TYP							
D2		1.70TYP							
E		0.25TYP							
E1		0.50TYP							
F		0.40TYP							







CONTACT US

Dioo is a professional design and sales corporation for high-quality and performance analog semiconductors. The company focuses on industry markets, such as, cell phone, handheld products, laptop, and medical equipment and so on. Dioo's product families include analog signal processing and amplifying, LED drivers and charger IC. Go to http://www.dioo.com for a complete list of Dioo product families

For additional product information, or full datasheet, please contact with our Sales Department or Representatives.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов:
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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